

Minutes of the IPT Meeting of Jan 6, 2004

Attendees:

DOE-PAO G. Pitonak

DOE HQ G. Nardella

ORNL J. Lyon

PPPL H. Neilson, R. Templon, W. Reiersen, J. Levine, R. Hawryluk, J. Malsbury, R. Strykowski

1. DOE update - Greg and Gene

Gene has confirmed with Anne that Case 2 will be the baseline profile. (Flat in 05, ramping up in 06, TEC=\$86.3M, CD-4 in May 2008). An e-mail from Gene making it official will follow (done).

2. Results/Impacts from PDR, Lehman, & EIR reviews - Hutch

The project continues to evaluate cost/schedule impacts from the reviews. Disposition plans are being prepared. The final reports will be officially transmitted to the project as soon as available (done).

3. Planning for CD2 review - All

The ESAAB to approve CD-2 is tentatively scheduled for Jan. 29.

NOTE: It is now looking like we will have to postpone the CD2 ESAAB until the week of Feb 2, 2004 due to HQ schedule conflicts.

Regarding deadlines:

- The EIR and PBR (Lehman) disposition plans are due to Greg this Thursday (1/8). They will be forwarded, via OFES, to the originating offices.
- We expect to get some relief on the due dates for the updated resource loaded schedule, cost and schedule backup for the changes, and derivatives such as the milestone and cost tables. These will likely be due Jan. 22 instead of 15. Whatever can be delivered sooner than that, will be delivered.
- The ECP needs to be approved by Anne but will not be part of the CD-2 package and can reach Anne after CD-2, which provides some more relief. It was agreed that this ECP should be limited to just those changes driven by the reviews and recent DOE changes in funding and scope.

4. Technical progress (Hutch)

There has been good progress on the technical front in the areas of MCWF CAD modeling, VV geometry and clearance issues, 350C bakeout analysis, and conductor testing.

The project has now issued a CAD model for the prototype MCWF that the suppliers are able to work with successfully. The project is in the process of verifying that all three coil types and the complete assembly can be successfully modeled.

Analysis of the plasma-to-vacuum vessel clearance issues shows that adequate clearance can be provided within the constraints of the current segmentation and joint design. Analysis of 350C vacuum vessel bakeout issues indicates that the vessel can be heated to 350C with mechanically attached tubes on the body and electrical strip heaters on the port ducts. Thermal expansion interferences are minor at most. The suppliers have been asked to estimate the cost of high-temperature stress relieving. The project has received the conductor for the first test of winding on a 3D surface. The winding form will be a closed twisted tee, now in fabrication. Winding is projected to start in January, which will satisfy the second-quarter joule milestone for FY-04. The order for the twisted racetrack winding form has been placed with Energy Industries of Ohio. This will be used for the next step in the winding program.

The project has developed a critical issues tracking list, based on the risks identified in the Risk Management Plan. The critical issues list facilitates day-to-day risk management and tracking by the Systems Integration Team. Some issues have already been resolved, as reported above. Key issues being tracking include: material properties data and finite-element model development critical for structural analysis; and coil-to-coil interferences during field-period assembly (recently recognized).

5. Project performance (Ron)

The November Cost Performance data was reviewed and at this time is in good shape. No issues were identified. Statusing and WAF revisions are underway in support of the finalization of the CD2 baseline. Following CD2, official baseline reporting via the PARS system will be initiated.

6. The next IPT meeting will be Tues January 20, 2004 at 2PM, as it looks like this is OK for most of us. Personnel at PPPL will meet in the DOE conference room.

Call-in number for 1/20/04 will be provided.

Thanks for your participation,
Greg